

IN THE CLAIMS

Please amend the claims as follows:

1. (Canceled)
2. (Currently Amended) A method of forming a package comprising:
supporting a die on a flexible substrate;
encapsulating the die with a die encapsulant;
folding a flap of the flexible substrate over the die encapsulant;
introducing fold adhesive between the folded flap of the flexible substrate and a surface
of the die encapsulant;
conforming the fold adhesive to the surface such that the fold adhesive is substantially
flat; and ~~The method of claim 1 further comprising~~
curing the fold adhesive, wherein the fold adhesive has a volumetric cure shrinkage of
less than about 0.8%.
3. (Original) The method of claim 2 wherein curing includes a partial cure of the fold
adhesive using a cure process with at least one of temperature and pressure, and then a
substantially full cure using a temperature batch cure process.
4. (Currently Amended) The method of claim 2 [[1]] further comprising plasma cleaning to
remove releasing agents on the surface of the die encapsulant and on a front side of the substrate
before dispensing the fold adhesive.
5. (Currently Amended) The method of claim 2 [[1]] wherein the fold adhesive is dispensed
onto the die encapsulant before the flexible substrate is folded over the die encapsulant.

6. (Original) The method of claim 2 wherein the volumetric cure shrinkage of the adhesive facilitates a back side of the flexible substrate at the folded flap to become a substantially flat upper surface of the package.

7. (Original) The method of claim 6 further comprising minimizing a z-height of the flexible substrate.

8. (Currently Amended) The method of claim 2 [[1]] further comprising supporting a top package upon the folded flap of the flexible substrate.

9. (Currently Amended) A method of forming a package comprising:
supporting a die on a flexible substrate;
encapsulating the die with a die encapsulant;
folding a flap of the flexible substrate over the die encapsulant;
introducing fold adhesive between the folded flap of the flexible substrate and a surface
of the die encapsulant;

conforming the fold adhesive to the surface such that the fold adhesive is substantially flat;

supporting a top package upon the folded flap of the flexible substrate; and ~~The method of claim 8 further comprising:~~

providing solder joints between the top package and a substantially flat upper surface of the folded flap of the flexible substrate; and

maximizing reliability of the solder joints by transferring a substantial amount of stress from the solder joints to the fold adhesive, wherein the fold adhesive is substantially compliant due to a Young's modulus of less than about 600 MPa at about room temperature, and an elongation at break greater than about 100% at about room temperature.

10. (Currently Amended) The method of claim 2 [[1]] wherein the fold adhesive is selected from the group consisting of at least one of silicone, a silicone modified epoxy, a polyimide—

siloxane based system, vinyl terminated silane, hydrogen terminated silane, platinum catalyst, fumed silica, polyimide siloxane, aliphatic epoxy, phenol hardener, imidazole catalyst, an epoxy, an amine end capped silicone, phosphine catalyst, a silica filler and other filler particles.

11. (Currently Amended) The method of claim 2 [[1]] wherein the fold adhesive is selected from the group consisting of at least one of silicone, a silicone modified epoxy, and a polyimide-siloxane based system.

12. (Currently Amended) A method of forming a package comprising:
supporting a die on a flexible substrate;
encapsulating the die with a die encapsulant;
folding a flap of the flexible substrate over the die encapsulant;
introducing fold adhesive between the folded flap of the flexible substrate and a surface
of the die encapsulant; and
conforming the fold adhesive to the surface such that the fold adhesive is substantially
flat. ~~The method of claim 1~~

wherein the fold adhesive is selected from the group consisting of at least one of vinyl terminated silane, hydrogen terminated silane, platinum catalyst, fumed silica and other filler particles.

13. (Currently Amended) The method of claim 2 [[1]] wherein the fold adhesive is selected from the group consisting of at least one of polyimide siloxane, aliphatic epoxy, phenol hardener, and imidazole catalyst.

14. (Currently Amended) The method of claim 2 [[1]] wherein the fold adhesive is selected from the group consisting of at least one of an epoxy, an amine end capped silicone, phosphine catalyst, and a silica filler.

Claims 15- 30.(Canceled)

31. (New) The method of claim 9 wherein the volumetric cure shrinkage of the adhesive facilitates a back side of the flexible substrate at the folded flap to become a substantially flat upper surface of the package.

32. (New) The method of claim 9 further comprising minimizing a z-height of the flexible substrate.

33. (New) The method of claim 12 further comprising curing the fold adhesive, wherein the fold adhesive has a volumetric cure shrinkage of less than about 0.8%.

34. (New) The method of claim 12 further comprising partial curing of the fold adhesive using a cure process with at least one of temperature and pressure, and then a substantially full cure using a temperature batch cure process.